

Development Trends of TWS Application Chips (pre-order)

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Abstracts

As Bluetooth technology advances and smartphone brands sequentially remove the 3.5-mm headphone jack from their phones, the TWS (True Wireless Stereo) market has continued to grow. With market competition heating up, application IC vendors for TWS have constantly upgraded their technology. Eying on the growth potential of TWS, IC design houses have tapped into this market. This report begins with the current development of the TWS market, followed by an analysis of the trends in the TWS application IC industry, and examines some leading IC design houses' deployment in the TWS market.



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